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Product Change Notification - JAON-26RCHI659 [\(Printer Friendly\)](#)

Date: 21 Sep 2015

Notification subject: CCB 1724 and 1724.01 Initial Notice: Qualification of CuPdAu wire and G700HA molding compound in products of the 90nm TSMC wafer technology in 100L (12x12mm) and 64L (10x10mm) TQFP package at MTAI

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and G700HA molding compound in selected products of the 90nm TSMC wafer technology available in 100L (12 x 12mm) and 64L (10 x 10mm) TQFP package at MTAI assembly site.

Pre Change:
Gold wire (Au) bond wire and SG-8300ECM molding compound

Post Change:
Palladium coated copper with gold flash (CuPdAu) bond wire and G700HA molding compound

Impacts to Data Sheet:
None

Reason for Change:
To improve on-time delivery performance by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire and G700HA molding compound.

Change Implementation Status:
In Progress

Estimated First Ship Date:
October 30, 2015 (date code: 1544)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
September 21, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-26RCHI659_QuaI_Plan.pdf](#)
[PCN_JAON-26RCHI659_Affected_CPN.pdf](#)
[PCN_JAON-26RCHI659_Affected_CPN.xls](#)

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